



Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

EXHIBIT 13 APPENDIX C: T-COIL DATA PLOT

PCS

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS_Ch. 25 z(axial)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 56.5 dB

ABM1 comp = 2.88 dB A/m

BWC Factor = 0.155041 dB

Location: 0.8, -3.8, 3.7 mm

General Scans_ 25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

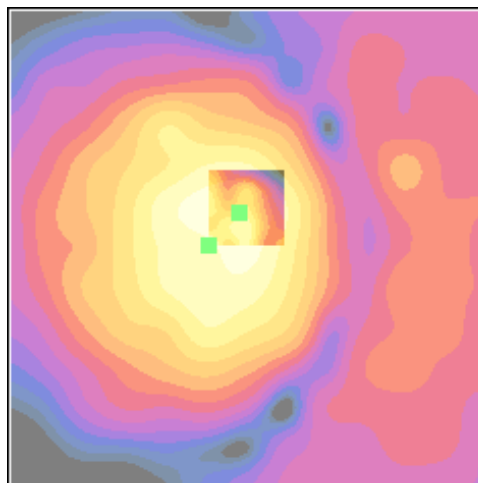
Cursor:

ABM1/ABM2 = 54.8 dB

ABM1 comp = 1.99 dB A/m

BWC Factor = 0.155041 dB

Location: 4, -0.2, 3.7 mm



0 dB = 668.5

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_S1360_TCoil_PCS_Ch. 25 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.0 dB

ABM1 comp = -6.51 dB A/m

BWC Factor = 0.155041 dB

Location: -6.7, 0, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

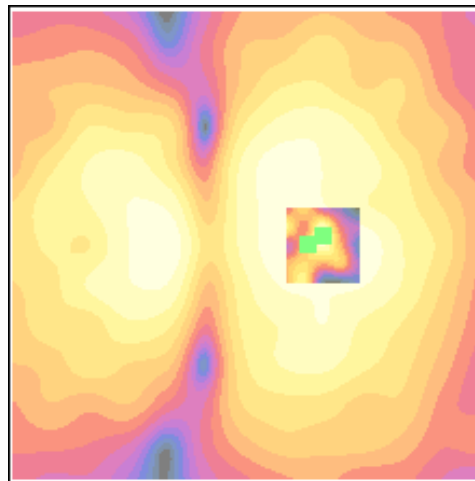
Cursor:

ABM1/ABM2 = 52.2 dB

ABM1 comp = -4.89 dB A/m

BWC Factor = 0.155041 dB

Location: -8.3, -1, 3.7 mm



0 dB = 317.3



Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS_ Ch. 25 y(transversal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

Measure Window Length: 1000ms

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.4 dB

ABM1 comp = -7.59 dB A/m

BWC Factor = 0.155041 dB

Location: 4.2, 12.1, 3.7 mm

General Scans_ 25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

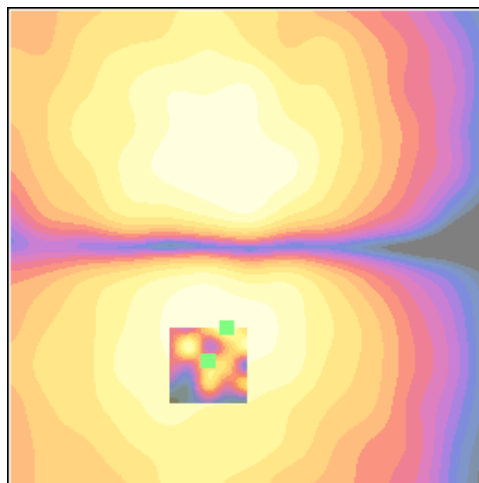
Cursor:

ABM1/ABM2 = 50.0 dB

ABM1 comp = -8.00 dB A/m

BWC Factor = 0.155041 dB

Location: 2.2, 8.5, 3.7 mm



0 dB = 330.7

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS Ch. 600 z(axial)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 53.2 dB

ABM1 comp = -0.232 dB A/m

BWC Factor = 0.155979 dB

Location: 1.7, -4.2, 3.7 mm

General Scans_ 600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

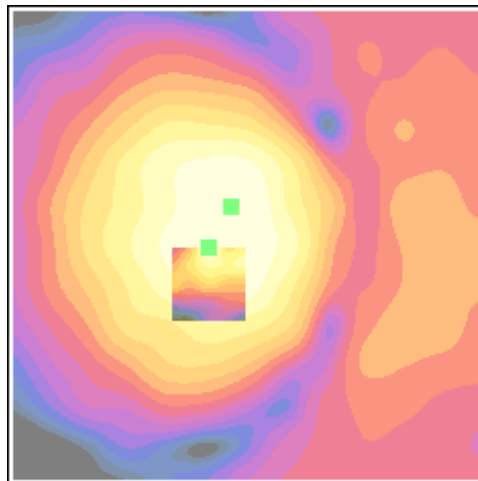
Cursor:

ABM1/ABM2 = 55.1 dB

ABM1 comp = 2.18 dB A/m

BWC Factor = 0.155979 dB

Location: 4.2, 0.2, 3.7 mm



0 dB = 455.0

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS Ch. 600 x (longitudinal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.6 dB

ABM1 comp = -7.15 dB A/m

BWC Factor = 0.155979 dB

Location: -5.8, -3.8, 3.7 mm

General Scans_ 600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

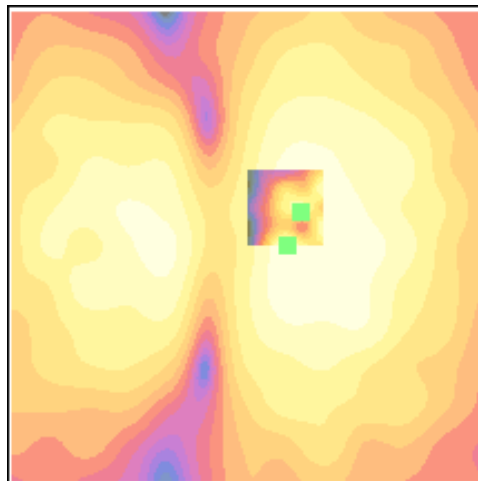
Cursor:

ABM1/ABM2 = 50.3 dB

ABM1 comp = -6.15 dB A/m

BWC Factor = 0.155979 dB

Location: -4.4, -0.2, 3.7 mm



0 dB = 300.6

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_S1360_TCoil_PCS_Ch. 600 y(transversal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 49.4 dB

ABM1 comp = -8.20 dB A/m

BWC Factor = 0.155979 dB

Location: 7.1, -9.6, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

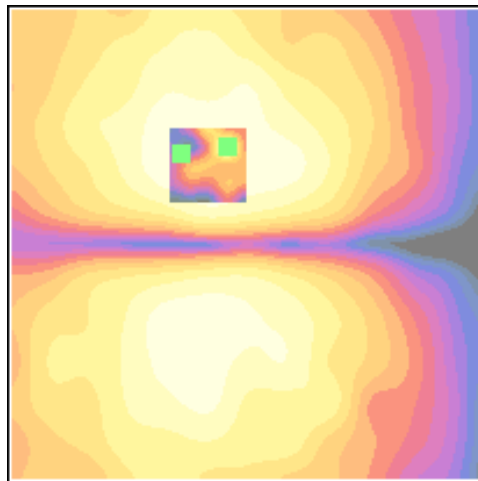
Cursor:

ABM1/ABM2 = 50.2 dB

ABM1 comp = -7.73 dB A/m

BWC Factor = 0.155979 dB

Location: 2.2, -10.3, 3.7 mm



0 dB = 296.3

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS_ Ch.1175 z(axial)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 $\square\square\square$ 1 deg C, Liquid T = 22.0 $\square\square\square$ 1 deg C

General Scans_ 1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 53.8 dB

ABM1 comp = 1.63 dB A/m

BWC Factor = 0.155041 dB

Location: 4.2, -2.9, 3.7 mm

General Scans_ 1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

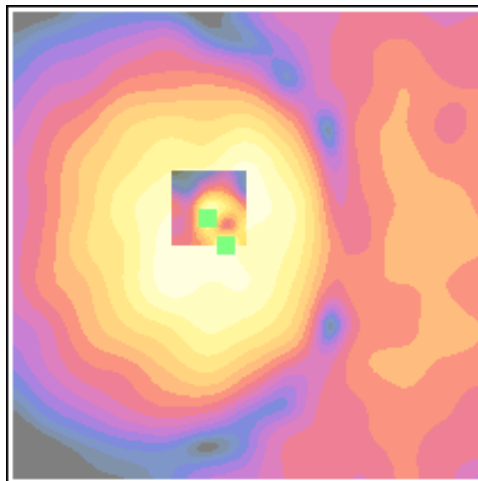
Cursor:

ABM1/ABM2 = 54.6 dB

ABM1 comp = 1.71 dB A/m

BWC Factor = 0.155041 dB

Location: 2.2, -0.2, 3.7 mm



0 dB = 487.3

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS_Ch. 1175 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.3 dB

ABM1 comp = -4.98 dB A/m

BWC Factor = 0.155041 dB

Location: -5.8, -4.2, 3.7 mm

General Scans_ 1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

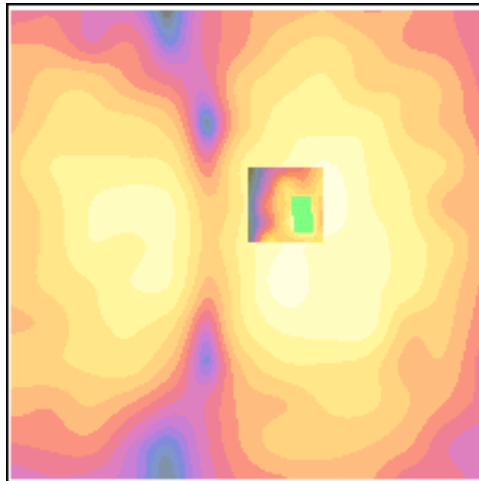
Cursor:

ABM1/ABM2 = 50.9 dB

ABM1 comp = -4.98 dB A/m

BWC Factor = 0.155041 dB

Location: -6, -2.4, 3.7 mm



0 dB = 366.1

Applicant	Kyocera
FCC ID:	V65S1360
Report #:	CT-S1360-13C-0513-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 05/03/2013

FCC_ S1360_TCoil_PCS_ Ch. 1175 y(transversal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/20/2012

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 50.2 dB

ABM1 comp = -7.75 dB A/m

BWC Factor = 0.155041 dB

Location: 0, 8.7, 3.7 mm

General Scans_ 1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

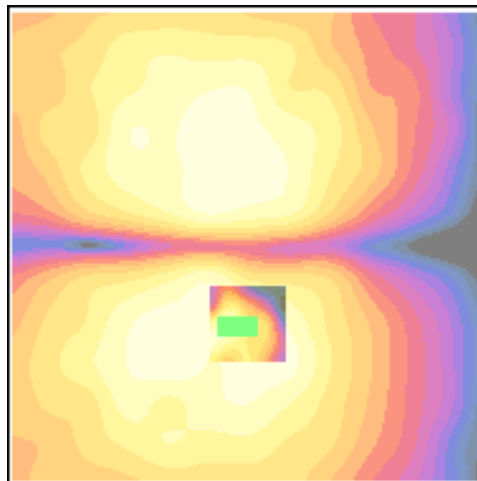
Cursor:

ABM1/ABM2 = 50.4 dB

ABM1 comp = -7.39 dB A/m

BWC Factor = 0.155041 dB

Location: 2.2, 8.5, 3.7 mm



0 dB = 322.5